



Material Content Data Sheet



Sales Product Name		BCR 196W H6327		Issued		25. September 2017			
MA#		MA000852520							
Package		PG-SOT323-3-1		Weight*		5.96 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	noble metal	gold	7440-57-5	0.005	0.08		841		
	non noble metal	arsenic	7440-38-2	0.000	0.00		9		
	inorganic material	silicon	7440-21-3	0.043	0.72	0.80	7181	8031	
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		88		
	non noble metal	titanium	7440-32-6	0.003	0.04		441		
	non noble metal	chromium	7440-47-3	0.008	0.13		1323		
	non noble metal	copper	7440-50-8	2.617	43.92	44.10	439107	440959	
wire	non noble metal	copper	7440-50-8	0.005	0.08	0.08	818	818	
encapsulation	organic material	carbon black	1333-86-4	0.031	0.53		5262		
	plastics	epoxy resin	-	0.674	11.31		113143		
	inorganic material	silicondioxide	60676-86-0	2.431	40.78	52.62	407841	526246	
leadfinish	non noble metal	tin	7440-31-5	0.133	2.23	2.23	22266	22266	
plating	noble metal	silver	7440-22-4	0.010	0.17	0.17	1680	1680	
*deviation	< 10%					Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com